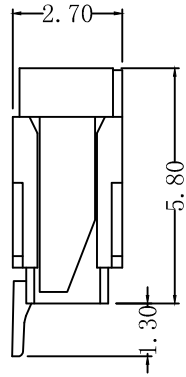
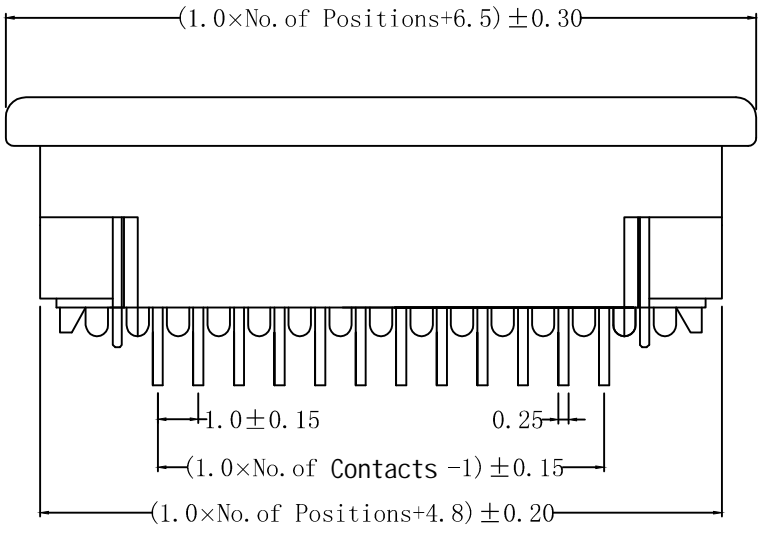
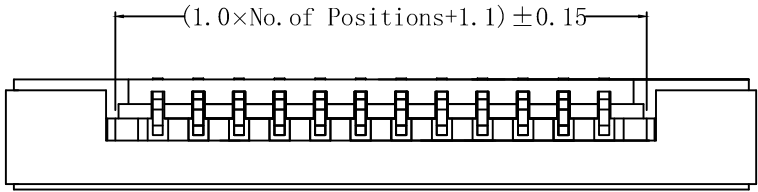
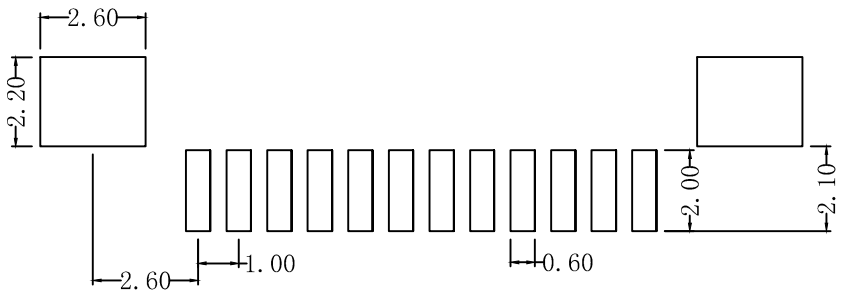


REV	DESCRIPTION	DATE



■ NOTE:
 MATERIAL:
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
 COVER: HIGH TEMPERATURE THERMOPLASTIC.
 CONTACT: COPPER ALLOY.
 HOLDDOWN: COPPER ALLOY.

■ PART NO.
 CNT-FPC100-XX-TDM-S10-270



RECOMMENDED PCB LAYOUT

CNT 肯耐特电子有限公司				GENERAL TOLERANCE		DRAWN	DATE	DWG. NO.		TITLE
				X.° ±5°	X. ±0.30	董道丽	20191011			
REV. 1.0 UNIT mm SCALE 1:1				.X° ±3°		CHECK	DATE	PART. NO.		FPC 1.0mm PITCH 单面 上接触 SMT 90°
				.XX° ±2°		.XX ±0.25	王芳芳	20191011	CNT-FPC100-XX-TDM-S10-270	
				.XXX° ±1°		APPROVE	DATE			
				.XXX ±0.15		王元中	20191011			